
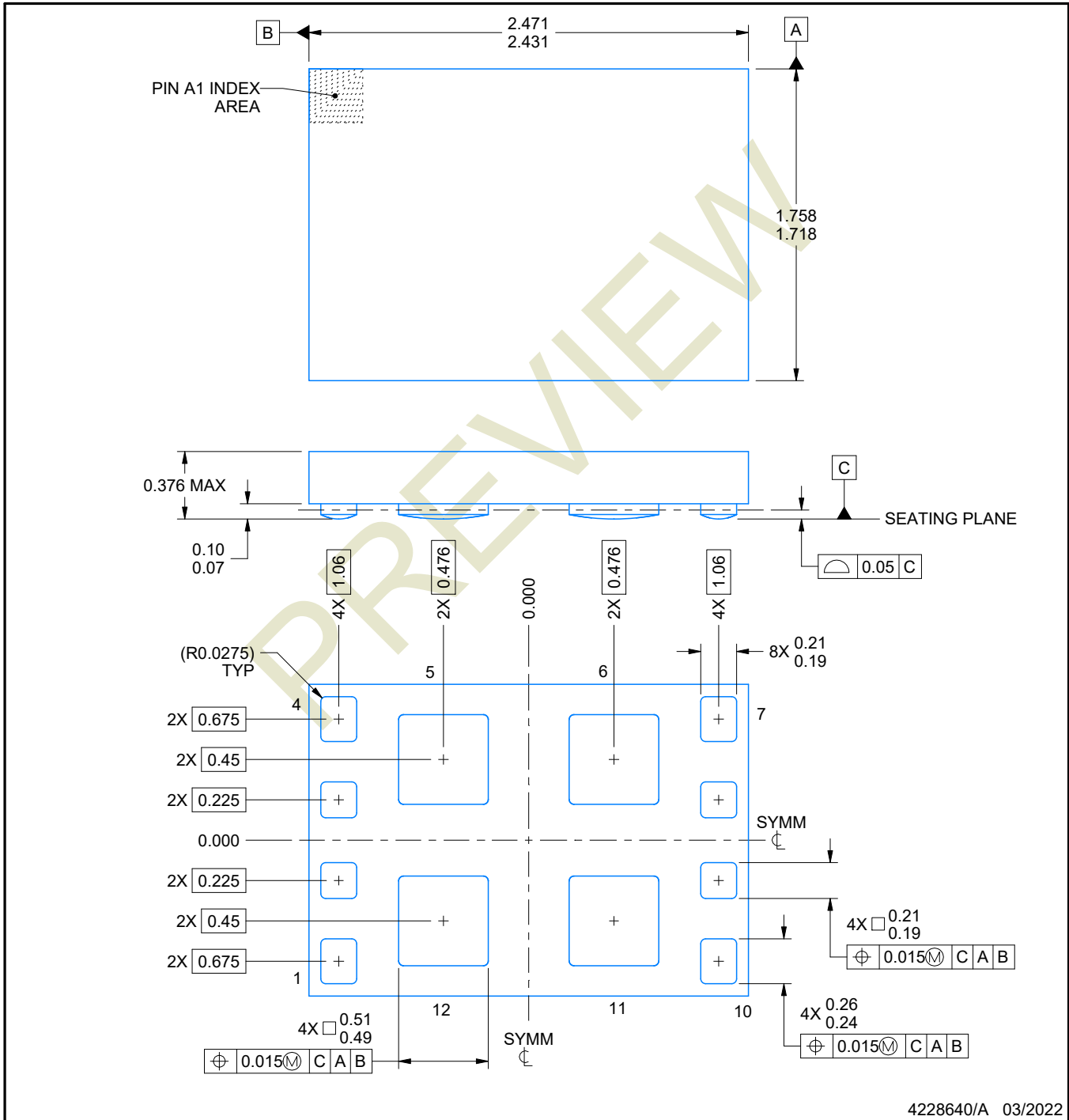
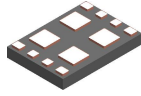


# DATA BOOK PACKAGE OUTLINE

PREVIEW

DRAFTER:	K. SINCERBOX	DATE:	2022		DIMENSIONS IN MILLIMETERS	
DESIGNER:		DATE:		 <b>TEXAS INSTRUMENTS</b> <small>SEMICONDUCTOR OPERATIONS</small>	CODE IDENTITY NUMBER	
CHECKER:	K. SINCERBOX	DATE:	2022		01295	
ENGINEER:	S. PHADKE	DATE:	2022	<b>ePOD, YWP0012A / PowerWCSP, 12 PIN, 0.45 MM PITCH</b>		
APPROVED:	D. CHIN & J. MARIANO	DATE:	2022			
RELEASED:	K. SINCERBOX	DATE:	2022			
TEMPLATE INFO:	EDGE# 4218519	DATE:	04/07/2016	SCALE NTS	SIZE A	
				<b>4228640</b>	REV <b>A</b>	PAGE 1 OF 5



NOTES:

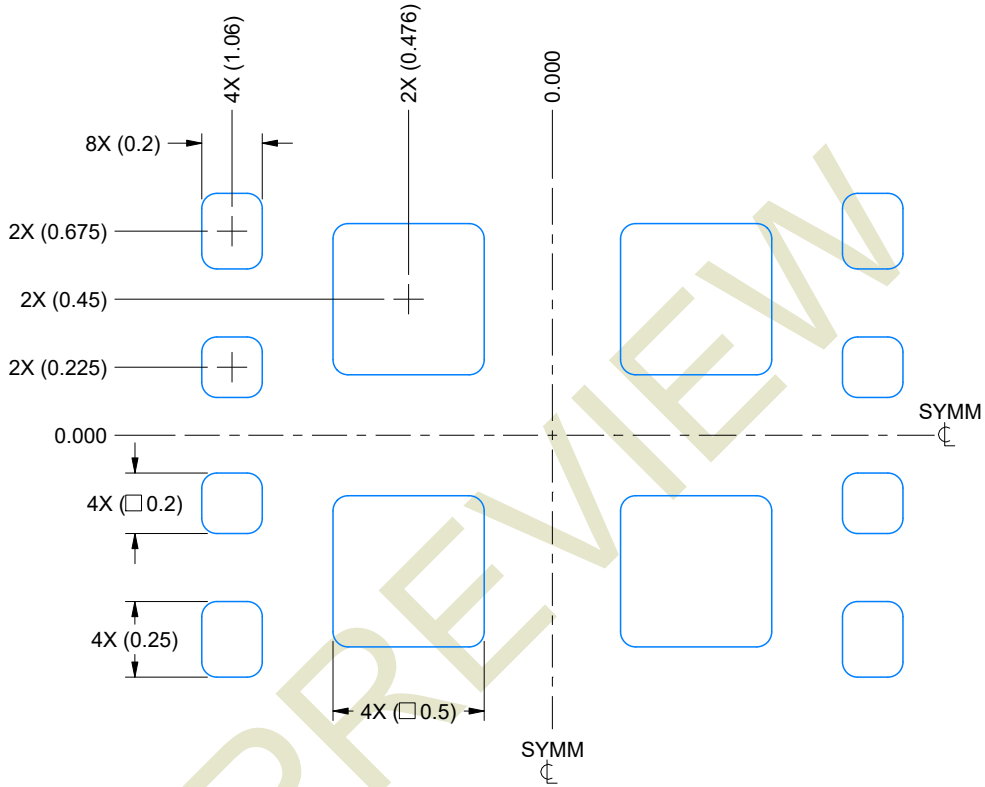
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.

# EXAMPLE BOARD LAYOUT

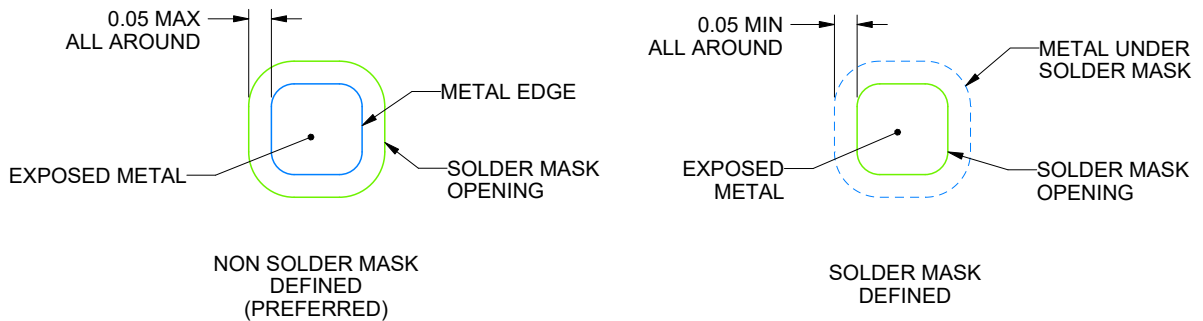
YWP0012A

PowerWCSP - 0.376 mm max height

POWER CHIP SCALE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 40X



SOLDER MASK DETAILS  
NOT TO SCALE

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NOTES: (continued)

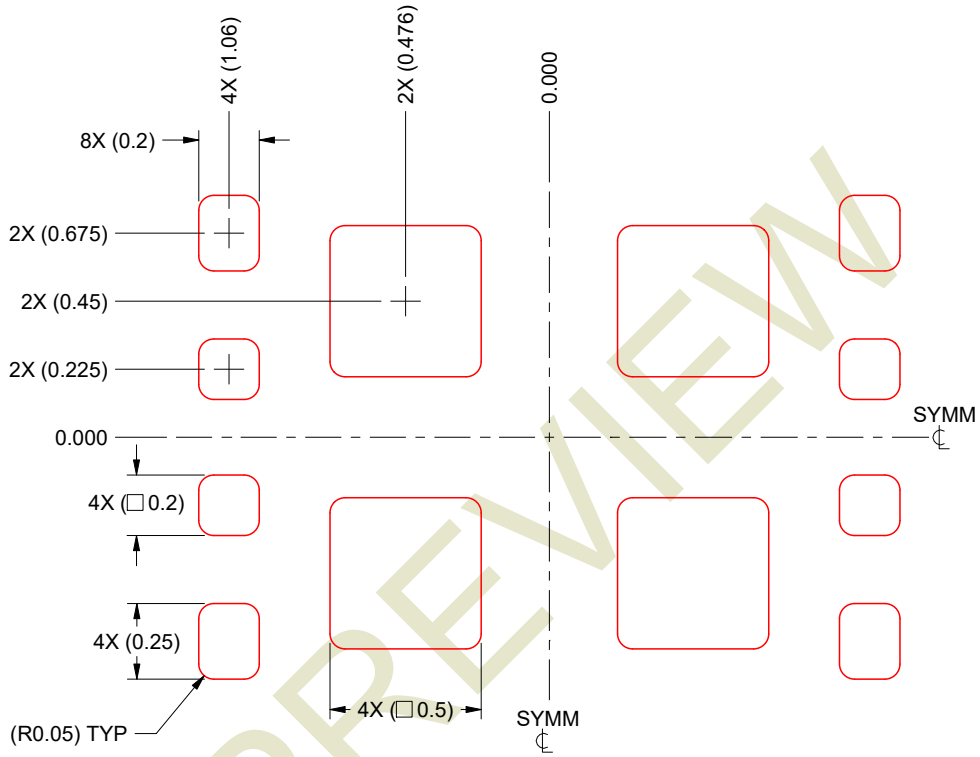
- Final dimensions may vary due to manufacturing tolerance considerations and also routing constraints. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).

# EXAMPLE STENCIL DESIGN

YWP0012A

PowerWCSP - 0.376 mm max height

POWER CHIP SCALE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.075 mm THICK STENCIL  
SCALE: 40X

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NOTES: (continued)

4. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release.

REVISIONS

REV	DESCRIPTION	ECR	DATE	ENGINEER / DRAFTER
A	RELEASE NEW DRAWING	2199296	2022	S. PHADKE / K. SINCERBOX

PREVIEW